

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

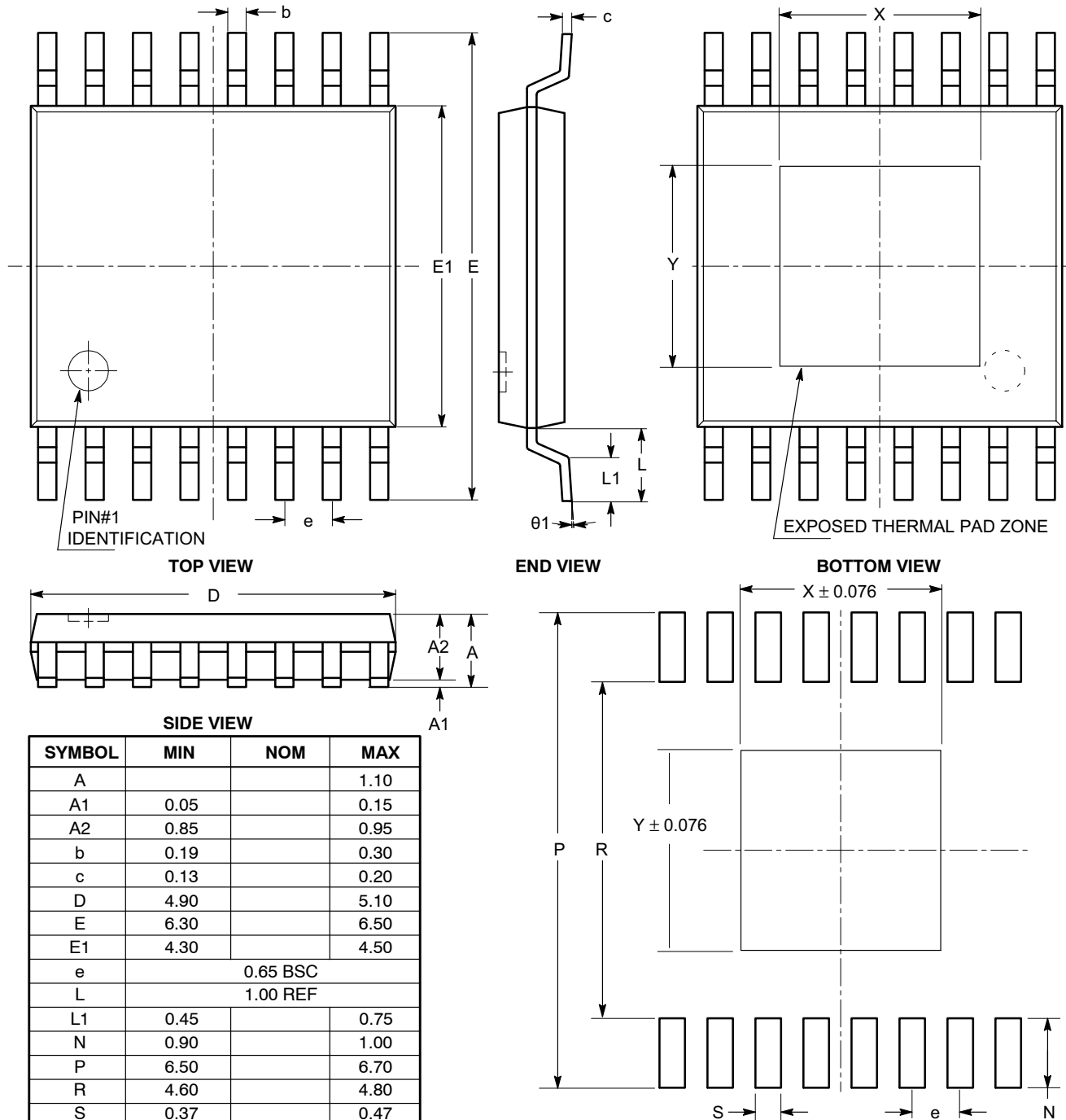
ON Semiconductor®



TSSOP16, 4.4x5 EXPOSED PAD

CASE 948AP-01
ISSUE A

DATE 18 MAR 2009



SIDE VIEW			
SYMBOL	MIN	NOM	MAX
A			1.10
A1	0.05		0.15
A2	0.85		0.95
b	0.19		0.30
c	0.13		0.20
D	4.90		5.10
E	6.30		6.50
E1	4.30		4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.45		0.75
N	0.90		1.00
P	6.50		6.70
R	4.60		4.80
S	0.37		0.47
θ	0°		8°
X		2.74 REF	
Y		2.74 REF	

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153 variations ABT.

LAND PATTERN

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